产品承认书 **SPECIFICATION FOR APPROVAL**

CUSTOMER:				
CUSTOMER P/N:				
CND-TEK P/N.:	G2401S			
DESCRIPTION:	1000 BASE-T MAGNETICS MODULES			
REF NO:				
REV/NO:	$\mathbf{A}/0$			
DATE:	2014-9-15			
ATTACHMENT:				
■ SPECIFICATION				
	OF SAMPLES PCS			

	V	CUSTOMER'S SIGNATURE	REMARK
FULL APPROVED			
CONDITIONAL APPROVED			
REJECTED			



公司地址: 深圳市南山区西丽镇阳光工业区5栋3楼 TEL: 86-755-29016433 FAX: 0755-27652977

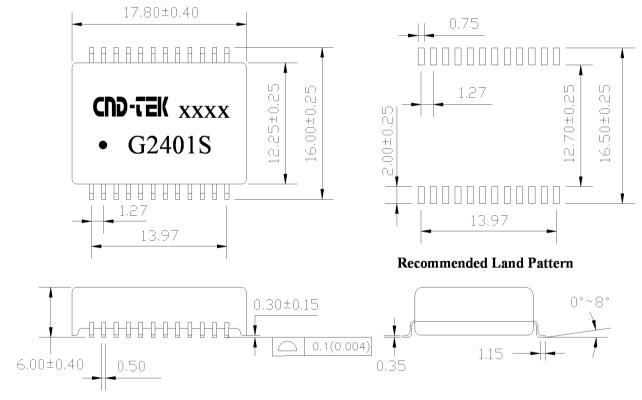
Email: cd001@cd-tek.com Http://www.cd-tek.com



1. FEATURES:

- 1.1 Designed for long haul Gigabit Ethernet 100/1000 Base-T, full duplex applications.
- 1.2 Supports four pairs of category 5 UTP cable, Cable interface for isolation and low common mode emissions.
- 1.3 Low profile Surface Mount Packaging designed for Hi-Temp Reflow Process
- 1.4 Compliant with IEEE 802.3ab standard for 1000 Base-T,Designed to support 1:1 Turns Ratio Transceivers.
- 1.5 Operating Temperature range: 0°C TO +70°C
- 1.6 Storage temperature range: -25 °C TO +125 °C

2. DIMENSIONS & MARKING

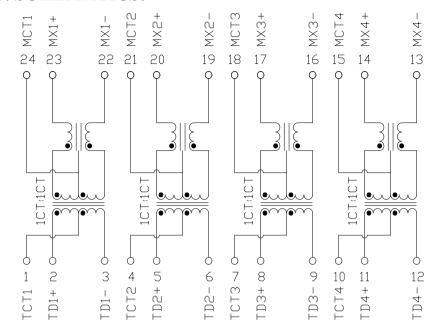


Note: 1, Dimension: mm

2. Unless otherwise specified, all tolerances are: ± 0.05 mm

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3. SCHEMATICS:



4.ELECTRICAL SPECIFICATIONS @25℃

4.1 OCL : 350 µH Min. @ 100 KHz, 100mV with 8mA DC Bias

4.2 Leakage Inductance: 0.5 μH Max. @ 100KHz, 0.2V

4.3 Cw/w: 28 pF Max. @ 100KHz, 0.2V

4.4 DCR: 0.9 Max.

4.5 Turns Ratio(±5%): 1CT:1(TX), 1CT:1(RX)

4.6 Polarity: 2-23, 5-20, 8-17, 11-14 In-Phase

4.7 Insertion Loss: -1.0 dB Max. @ 1-100MHz

4.8 Return Loss: -16 dB Min. @ 1-30MHz

-12 dB Min. @ 30-60 MHz

-10 dB Min.@ 60-80 MHz

4.9 Cross Talk: -42 dB Min.@ 1-60 MHz

-35 dB Min.@ 60-100 MHz

4.10 Common Mode Rejection : -40 dB Min.@ 1-30 MHz

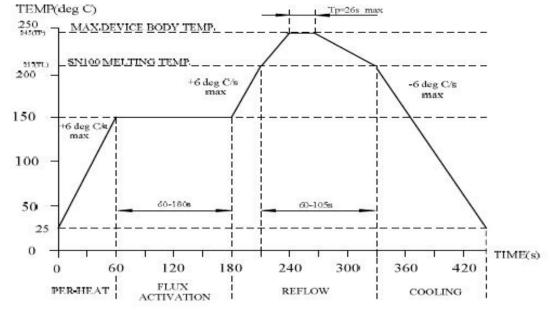
-35 dB Min.@ 60 MHz

-30 dB Min.@ 80-100 MHz

4.11 Isolation HI-POT: 1500Vrms 1mA 1Second

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5. Recommended Lead Free IR Reflow Soldering Curve:



COMPONENT BODY REFLOW TEMPERATURE PROFILE

Item	Soldertechnique simulation	Temperature (°C)	Time(s)	Temperature ramp/immersion and emersion rate
1	Solder iron	350±10 (solder irno temp)	4~5	
2	Vapor phase reflow	215±5 (vapor temp)	60±5	
3	IR/convection reflow	255±5 (component temp)	30±5	1°C/s~4°C/s time above 183°C 90s~120s

Note: The curve includes recommended value only, please adjust your equipment to make sure the solder process. Details please refers to the standard J-STD-020.

6. Reliability Test Criteria:

- 6.1 Terminal strength: Pull test withstand 9.8N 60+/-0.5S no looseness or movement.
- 6.2 Solderbility: Dipped in 245°C+/-5°C molten solder for 3+/-0.5 seconds,95% min shall be smooth any and bright.
- 6.3 Resistance to soldering heat: Convection reflow condition setting: peak temperature at $260^{\circ}\text{C}+0/-5^{\circ}\text{C}$ above 217°C for 90-180 seconds, ramp-up rate 2-3 °C/s. Ramp-down rate 6 °C/s Max. No mechanical problem found. No electrical failure found per our specification.
- 6.4 Vibration: 1.5mm amplitude total excursion 10-55-10 Hz traversed in 1minute, x.y.z, axis for 2 hours. Shall not be any abnormality.
- 6.5 Random drop (Packing condition): Height 60cm, 3 times on the wood floorboard ,shall not be any abnormality.
- 6.6 Dry heat: 100+/-2 °C 96 hours.
- 6.7 Cold: -20+/-2°C 96 hours.
- 6.8 Damp Heat: $60+/-2^{\circ}$ C, 93+/-3% RH 96 hours.
- 6.9 Change of temperature: exposed 5 cycle; each consisting of 30 minutes at $-20+/-2^{\circ}$ C, 2-3 minutes at $20+/-2^{\circ}$ C, 30 minutes at $85+/-2^{\circ}$ C, 2-3 minutes at $20+/-2^{\circ}$ C.

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